



High power cycling capability
Low on-state and switching losses
Designed for traction and industrial applications

Phase Control Thyristor Type T123-160-36

Mean on-state current		I _{TAV}		160 A	
Repetitive peak off-state voltage		V _{DRM}		3000...3600 V	
Repetitive peak reverse voltage		V _{RRM}			
Turn-off time		t _q		400, 500 μs	
V _{DRM} , V _{RRM} , V	3000	3200	3400	3600	
Voltage code	30	32	34	36	
T _j , °C	-60...+125				

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Maximum allowable mean on-state current	A	160 200	$T_c=97\text{ }^{\circ}\text{C}$, Double side cooled $T_c=85\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	251	$T_c=97\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	3.2 3.5	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
			3.5 4.0	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
I^2t	Safety factor	$A^2s\cdot 10^3$	50 60	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
			50 60	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt\geq 1\text{ A}/\mu\text{s}$
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	3000...3600	$T_{j\text{ min}} < T_j < T_{j\text{ max}}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	3100...3700	$T_{j\text{ min}} < T_j < T_{j\text{ max}}$; 180° half-sine wave; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.6\cdot V_{DRM}$ $0.6\cdot V_{RRM}$	$T_j=T_{j\text{ max}}$; Gate open	

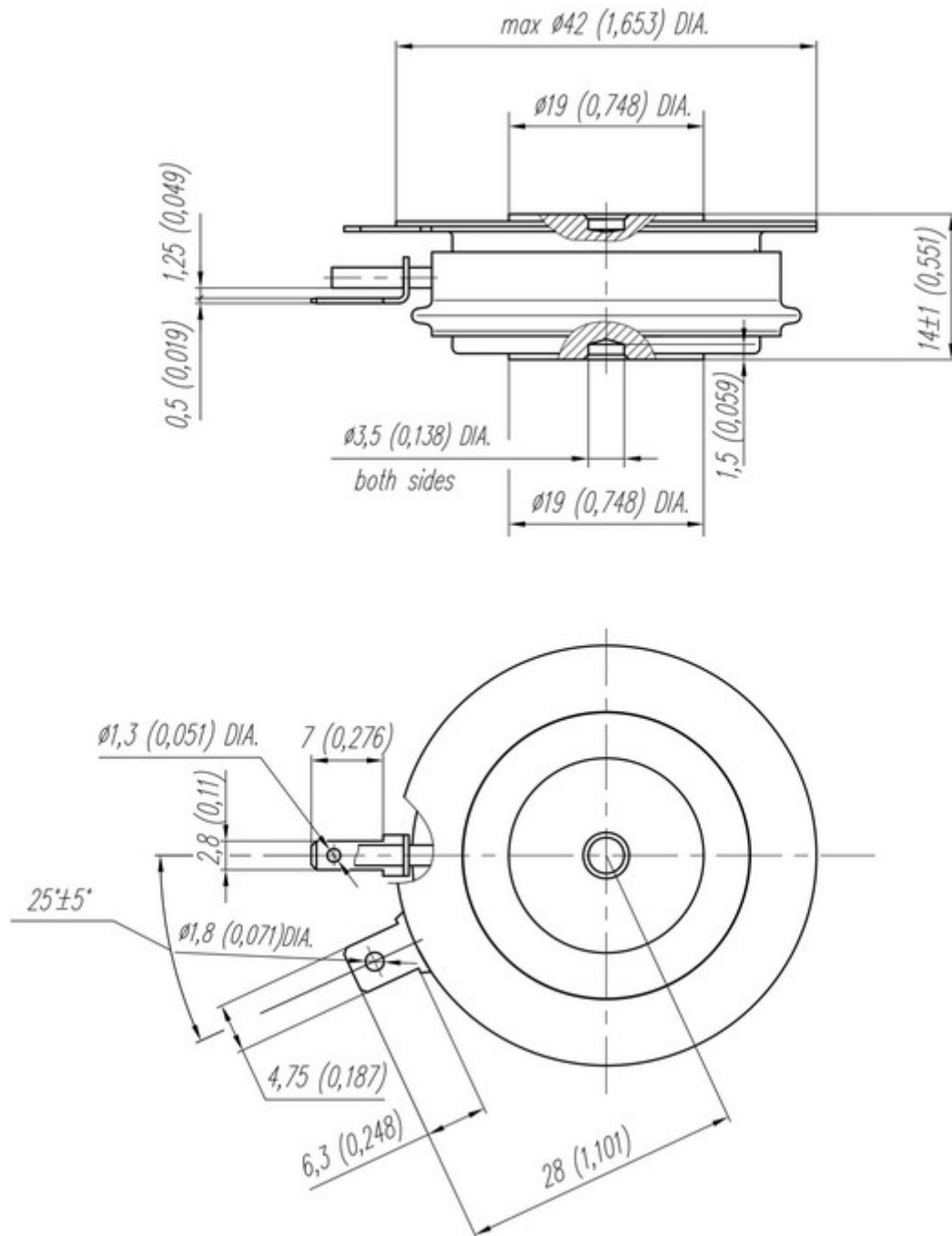
TRIGGERING				
I_{FGM}	Peak forward gate current	A	5	$T_j = T_{j\max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	3	$T_j = T_{j\max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	250	$T_j = T_{j\max}$; $V_D = 0.67 \cdot V_{DRM}$; $I_{TM} = 2 I_{TAV}$; Gate pulse: $I_G = 2$ A; $t_{GP} = 50 \mu$ s; $di_G/dt \geq 2$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	$^{\circ}$ C	-60...+50	
T_j	Operating junction temperature	$^{\circ}$ C	-60...+125	
MECHANICAL				
F	Mounting force	kN	5.0...7.0	
a	Acceleration	m/s ²	50 100	Device unclamped Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V _{TM}	Peak on-state voltage, max	V	2.30	T _j =25 °C; I _{TM} =503 A	
V _{T(TO)}	On-state threshold voltage, max	V	0.95	T _j =T _{j max} ;	
r _T	On-state slope resistance, max	mΩ	3.000	0.5 π I _{TAV} < I _T < 1.5 π I _{TAV}	
I _L	Latching current, max	mA	500	T _j =25 °C; V _D =12 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs	
I _H	Holding current, max	mA	250	T _j =25 °C; V _D =12 V; Gate open	
BLOCKING					
I _{DRM} , I _{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	70	T _j =T _{j max} ; V _D =V _{DRM} ; V _R =V _{RRM}	
(dv _D /dt) _{crit}	Critical rate of rise of off-state voltage ¹⁾	V/μs	200, 320, 500, 1000	T _j =T _{j max} ; V _D =0.67·V _{DRM} ; Gate open	
TRIGGERING					
V _{GT}	Gate trigger direct voltage, max	V	4.00 2.50 2.00	T _j = T _{j min} T _j =25 °C T _j = T _{j max}	V _D =12 V; I _D =3 A; Direct gate current
I _{GT}	Gate trigger direct current, max	mA	500 300 200	T _j = T _{j min} T _j = 25 °C T _j = T _{j max}	
V _{GD}	Gate non-trigger direct voltage, min	V	0.25	T _j =T _{j max} ; V _D =0.67·V _{DRM} ;	
I _{GD}	Gate non-trigger direct current, min	mA	10.00	Direct gate current	
SWITCHING					
t _{gd}	Delay time, max	μs	3.00	T _j =25 °C; V _D =1500 V; I _{TM} =I _{TAV} ; di/dt=200 A/μs; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥2 A/μs	
t _q	Turn-off time ²⁾ , max	μs	400, 500	dv _D /dt=50 V/μs; T _j =T _{j max} ; I _{TM} = I _{TAV} ; di _R /dt=-10 A/μs; V _R =100V; V _D =0.67·V _{DRM}	
Q _{rr}	Recovered charge, max	μC	920	T _j =T _{j max} ; I _{TM} = 115 A;	
t _{rr}	Reverse recovery time, max	μs	31	di _R /dt=-5 A/μs;	
I _{rr}	Reverse recovery current, max	A	59	V _R =100 V	

THERMAL					
R _{thjc}	Thermal resistance, junction to case, max	°C/W	0.0800	Direct current	Double side cooled
R _{thjc-A}			0.1760		Anode side cooled
R _{thjc-K}			0.1440		Cathode side cooled
R _{thck}	Thermal resistance, case to heatsink, max	°C/W	0.0100	Direct current	
MECHANICAL					
m	Weight, max	g	70		
D _s	Surface creepage distance	mm (inch)	7.94 (0.313)		
D _a	Air strike distance	mm (inch)	5.00 (0.197)		

PART NUMBERING GUIDE							NOTES														
T	123	160	36	A2	E2	N	1) Critical rate of rise of off-state voltage														
1	2	3	4	5	6	7	<table><tr><td>Symbol of Group</td><td>P2</td><td>K2</td><td>E2</td><td>A2</td></tr><tr><td>$(dv_D/dt)_{crit}, \text{ V}/\mu\text{s}$</td><td>200</td><td>320</td><td>500</td><td>1000</td></tr></table>					Symbol of Group	P2	K2	E2	A2	$(dv_D/dt)_{crit}, \text{ V}/\mu\text{s}$	200	320	500	1000
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1. Phase Control Thyristor 2. Design version 3. Mean on-state current, A 4. Voltage code 5. Critical rate of rise of off-state voltage 6. Group of turn-off time $(dv_D/dt=50 \text{ V}/\mu\text{s})$ 7. Ambient conditions: N – normal; T – tropical							2) Turn-off time $(dv_D/dt=50 \text{ V}/\mu\text{s})$														
							<table><tr><td>Symbol of group</td><td colspan="2">H2</td><td colspan="2">E2</td></tr><tr><td>$t_{q}, \mu\text{s}$</td><td colspan="2">400</td><td colspan="2">500</td></tr></table>					Symbol of group	H2		E2		$t_{q}, \mu\text{s}$	400		500	
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All dimensions in millimeters (inches)

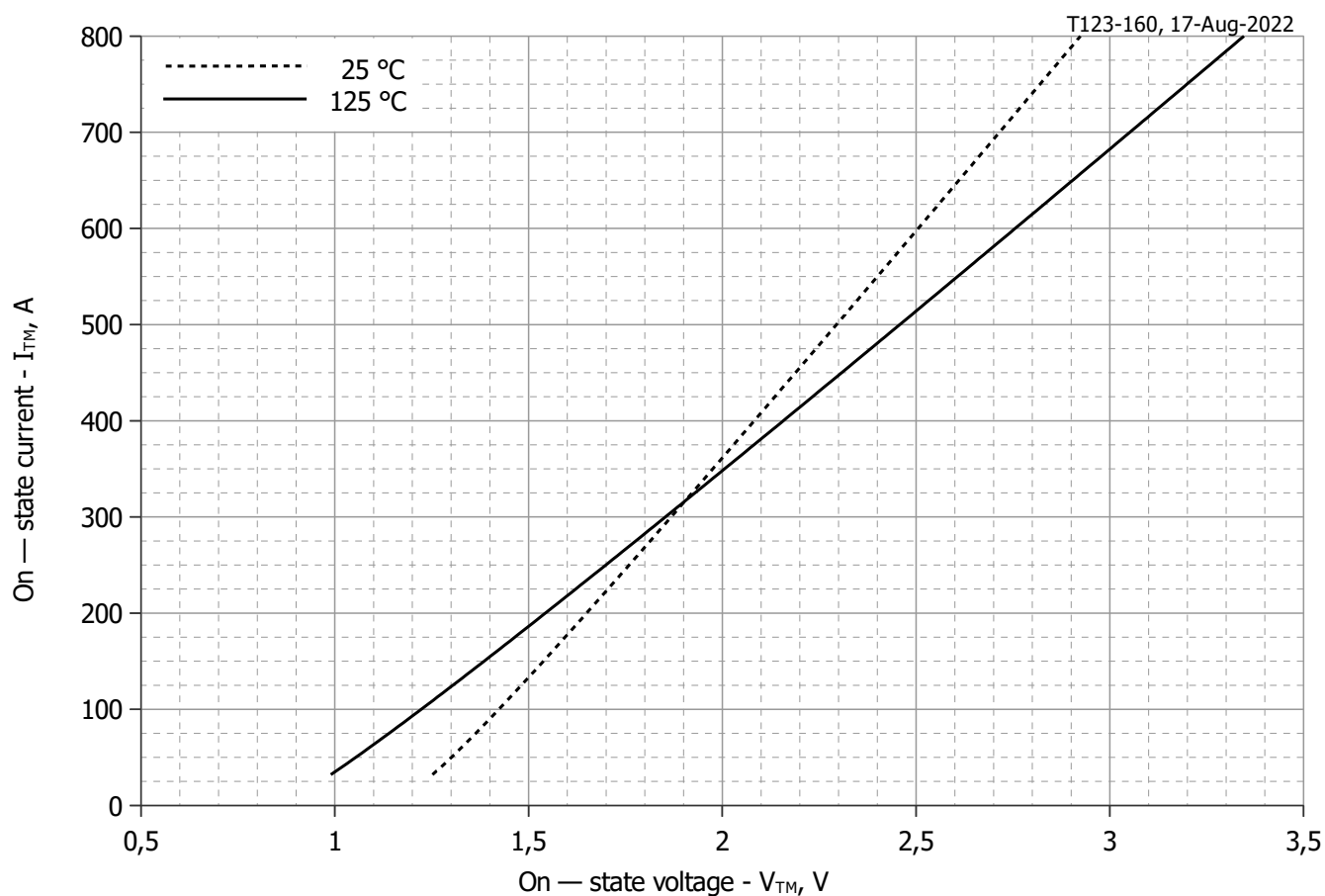


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients	
	$T_j = 25^\circ\text{C}$	$T_j = T_{j \max}$
A	1.10015909	0.84963431
B	0.00201525	0.00272346
C	0.02077061	-0.00496092
D	0.00257932	0.01239927

On-state characteristic model (see Fig. 1).

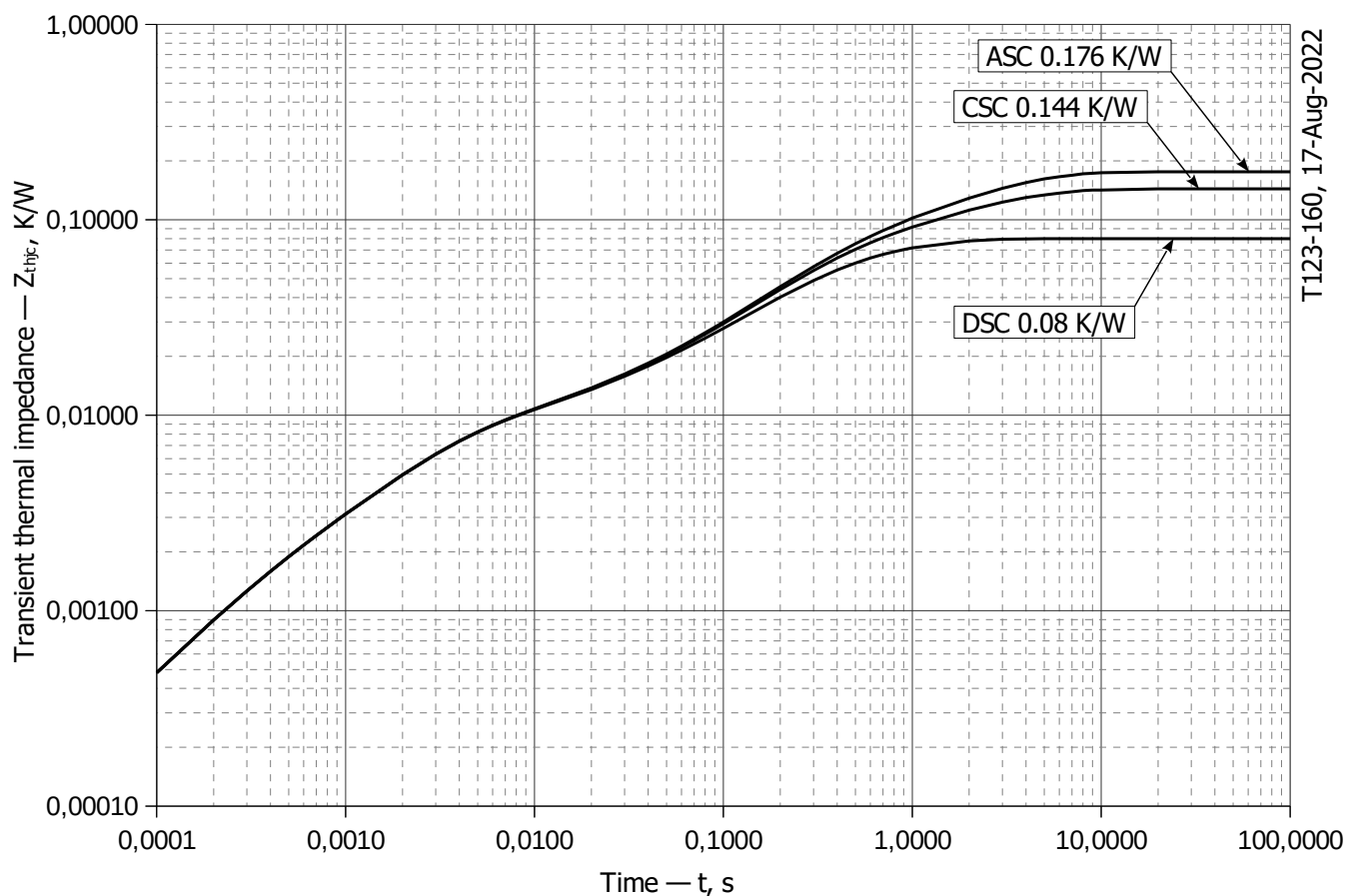


Fig 2 – Transient thermal impedance Z_{thjc} vs. time t

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i , K/W	0.03326	0.02722	0.009282	0.00277	0.00676	0.0006989
τ_i , s	0.2708	0.7617	0.1786	0.01535	0.002756	0.0002959

DC Anode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.09286	0.04384	0.002686	0.006513	0.0006586	0.02964
τ_i , s	2.666	0.2696	0.01249	0.002653	0.0002815	0.894

DC Cathode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.06238	0.04339	0.002668	0.006627	0.0006771	0.02799
τ_i , s	2.658	0.2589	0.0136	0.0027	0.0002885	0.8166

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2).

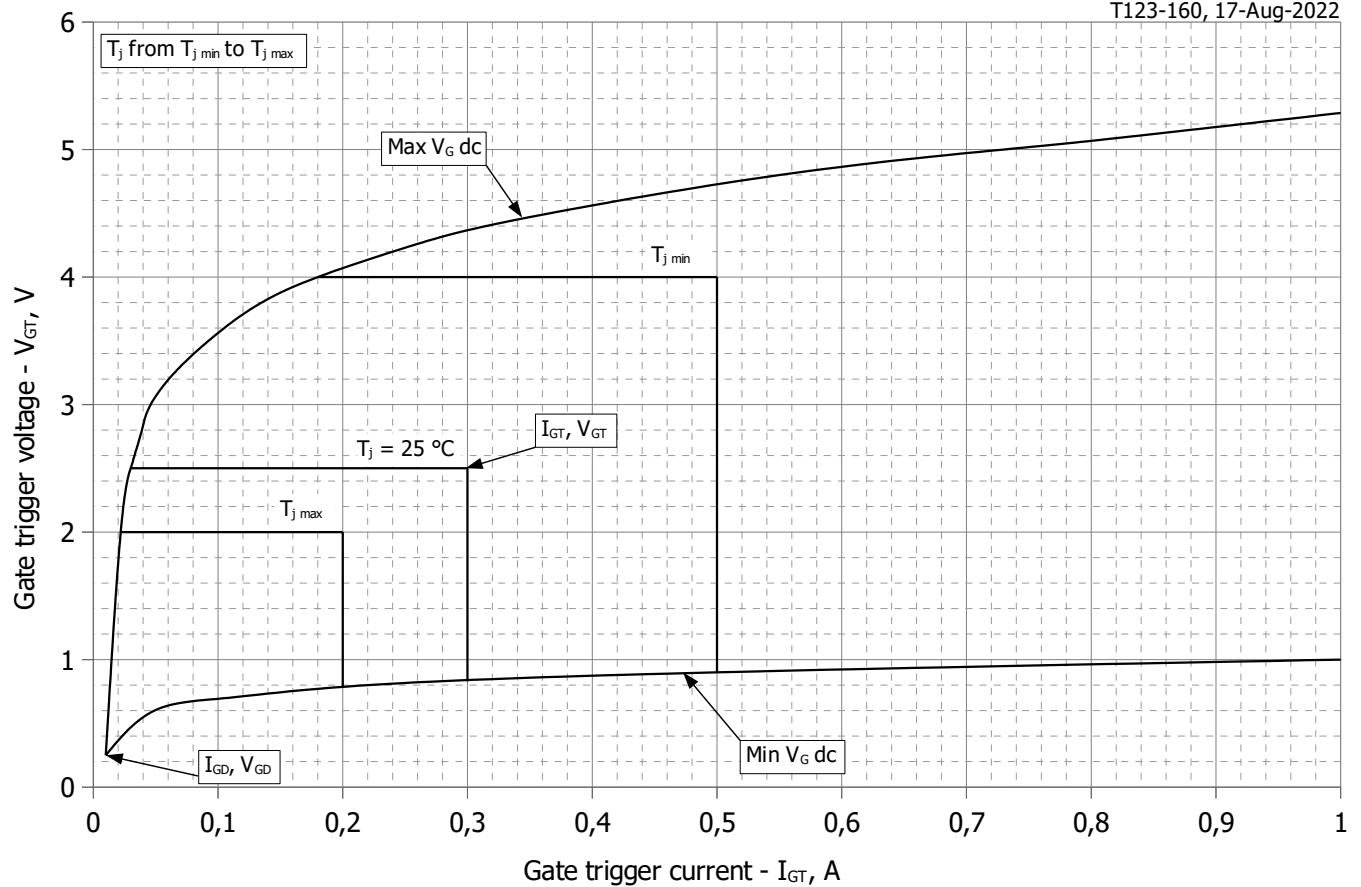


Fig 3 – Gate characteristics – Trigger limits

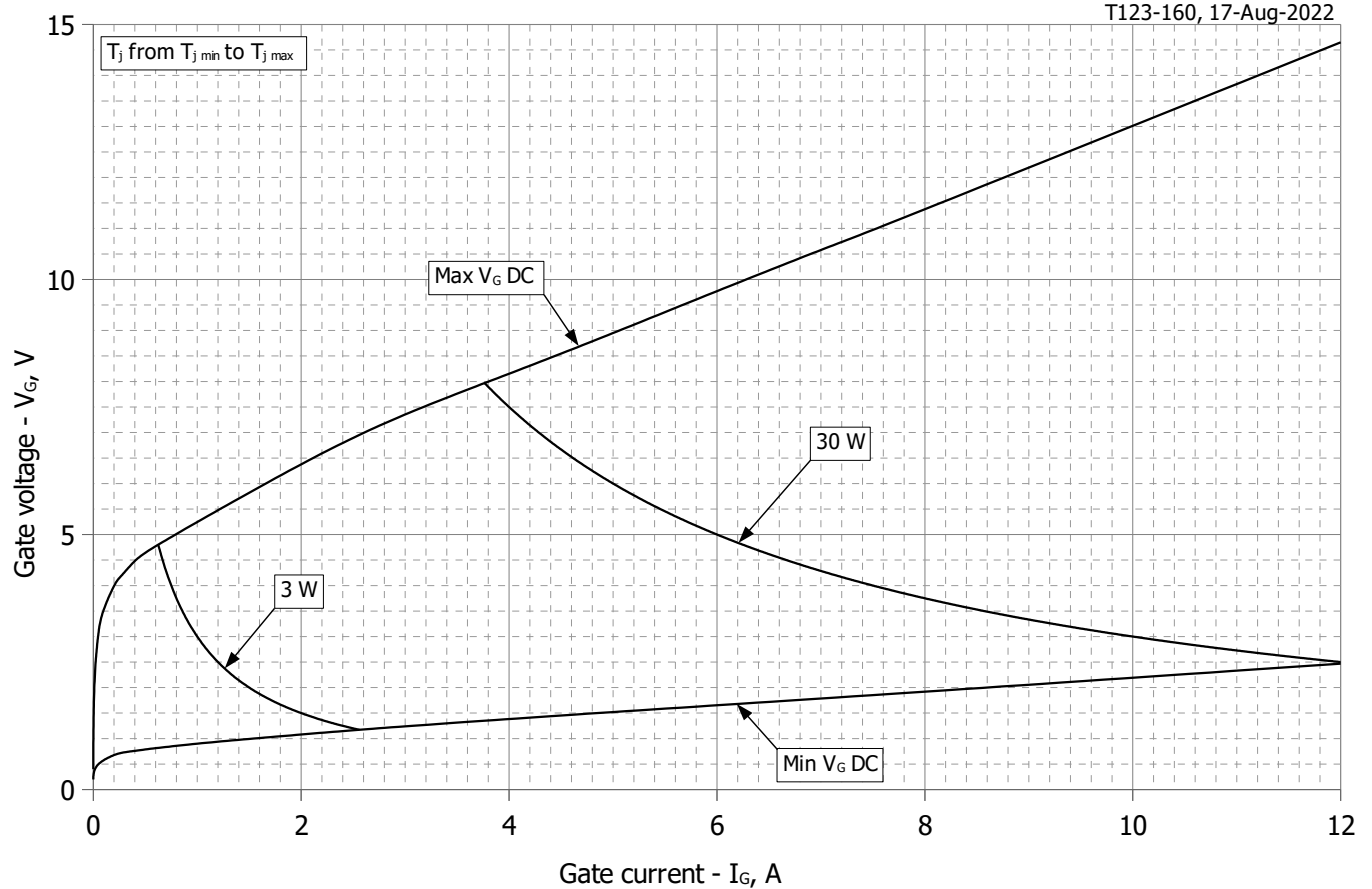


Fig 4 – Gate characteristics – Power curves

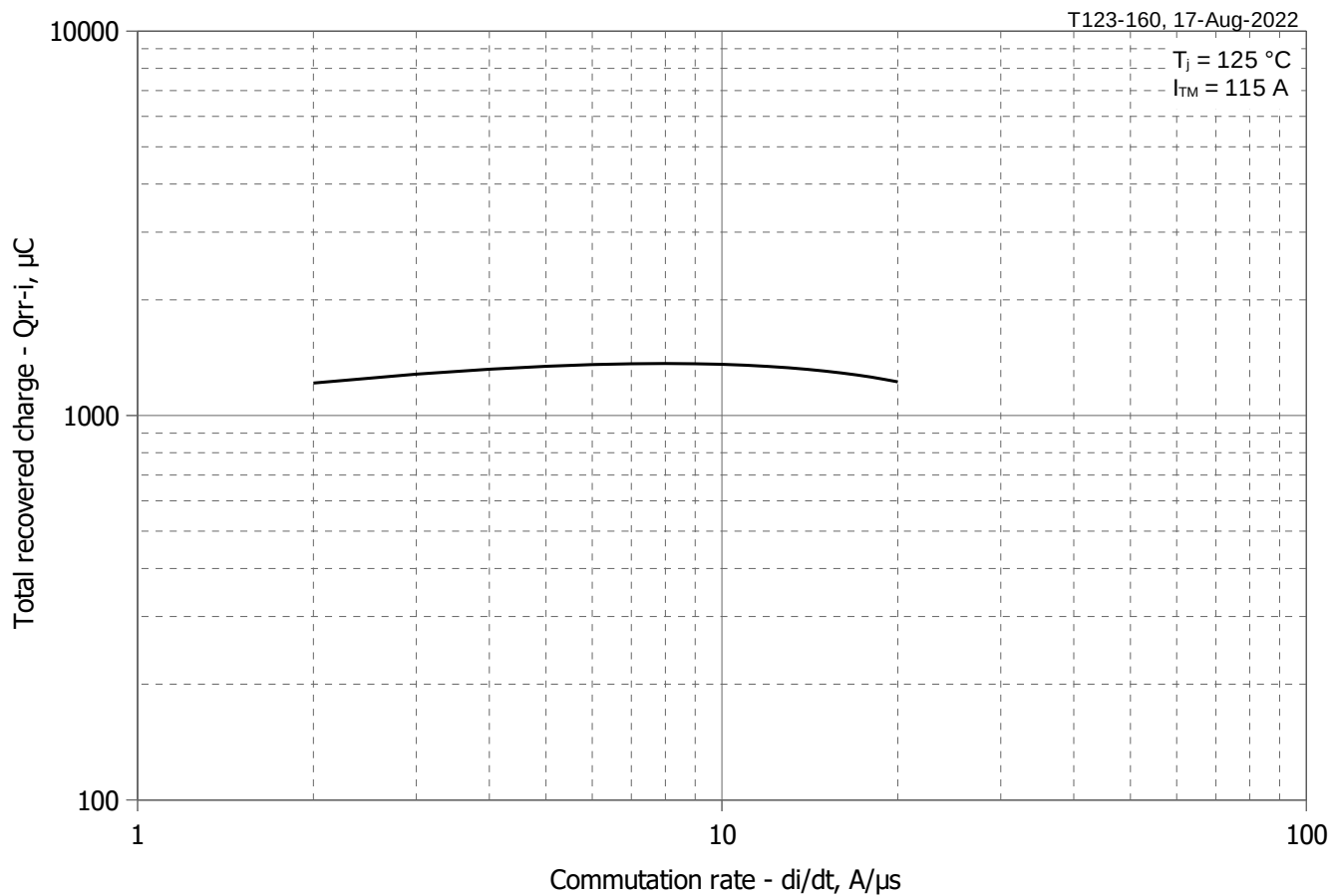


Fig 5 – Maximum recovered charge Q_{rr-i} (integral) vs. commutation rate di_R/dt

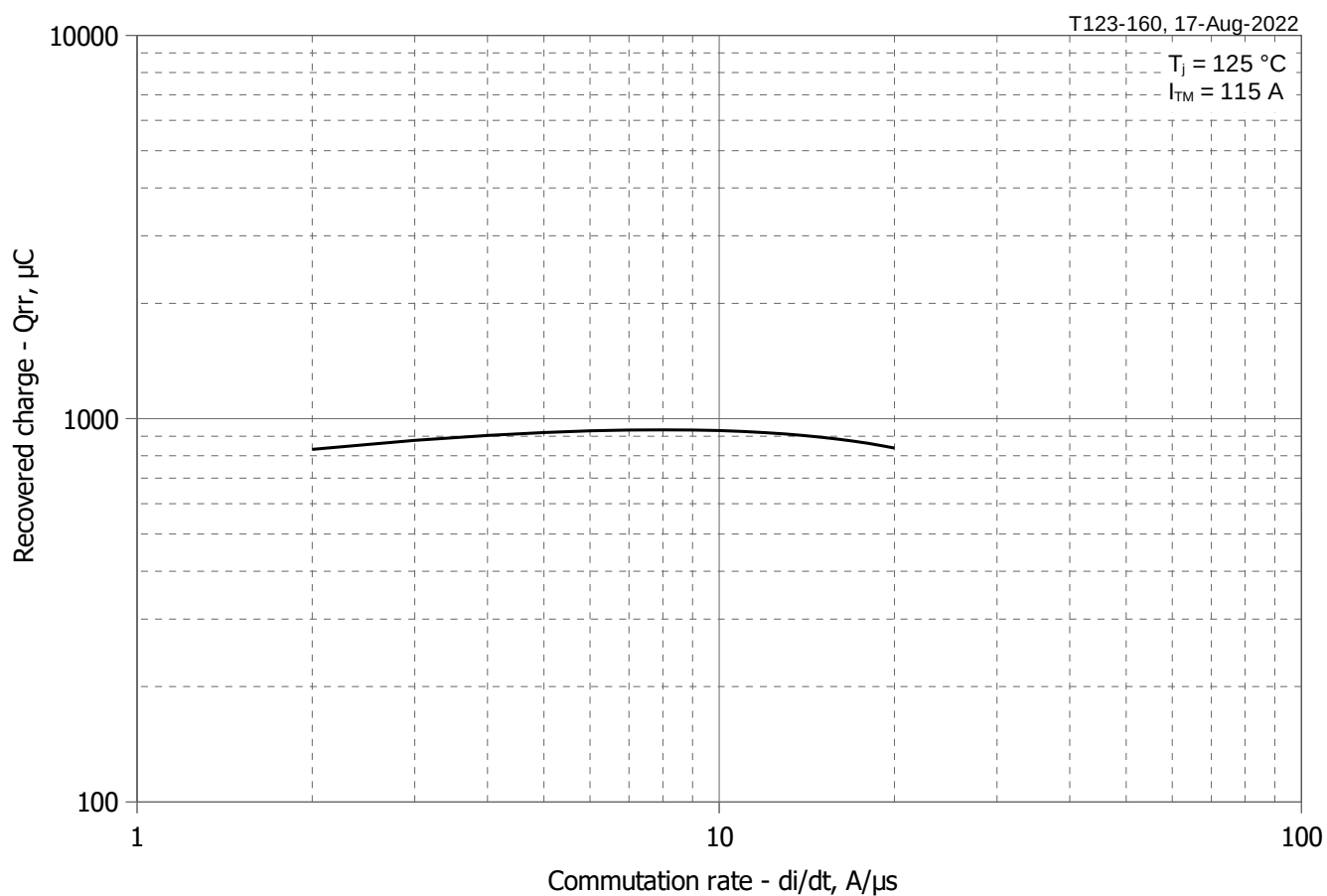


Fig 6 – Maximum recovered charge Q_{rr} vs. commutation rate di_R/dt (25% chord)

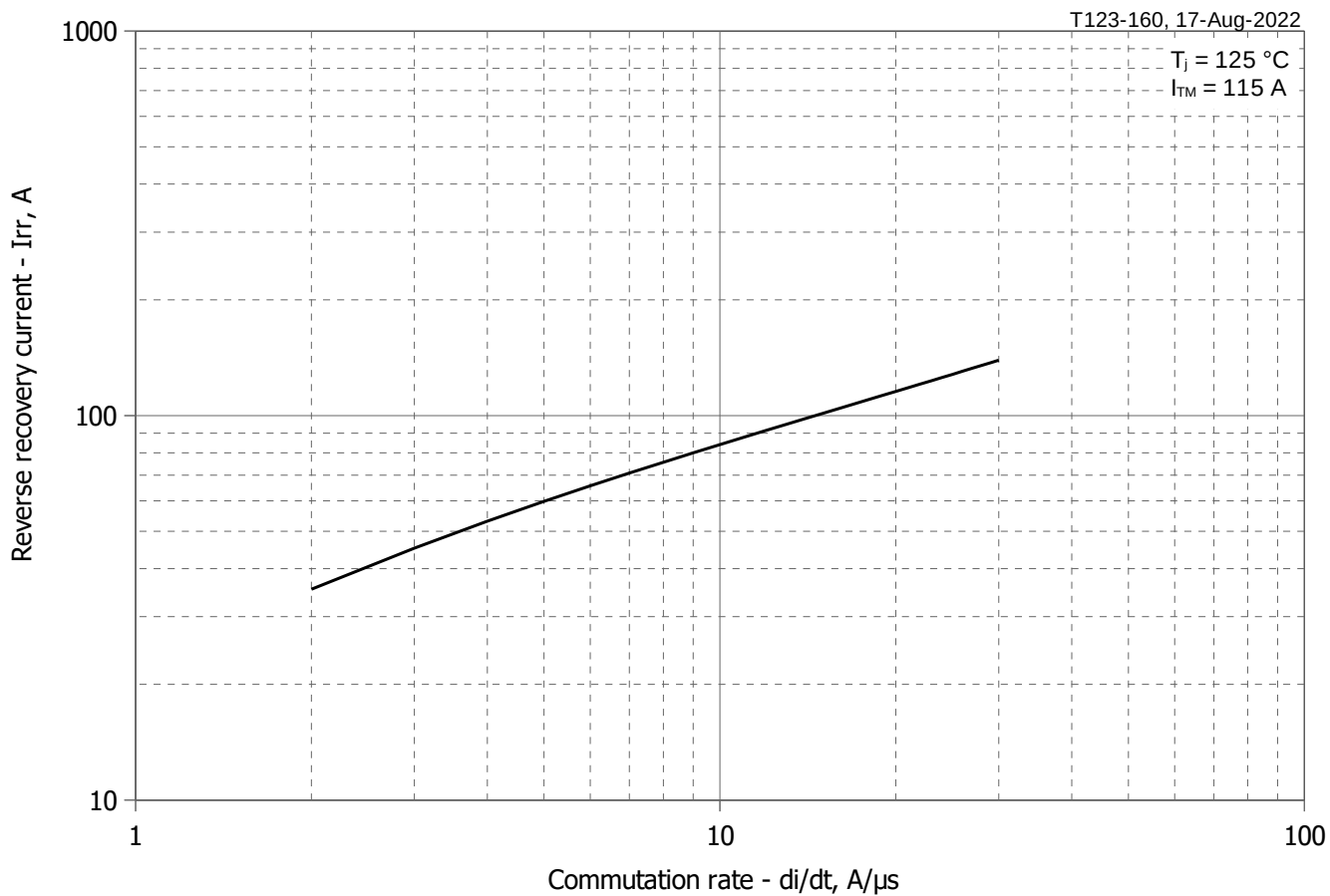


Fig 7 – Maximum reverse recovery current I_{rr} vs. commutation rate di_R/dt

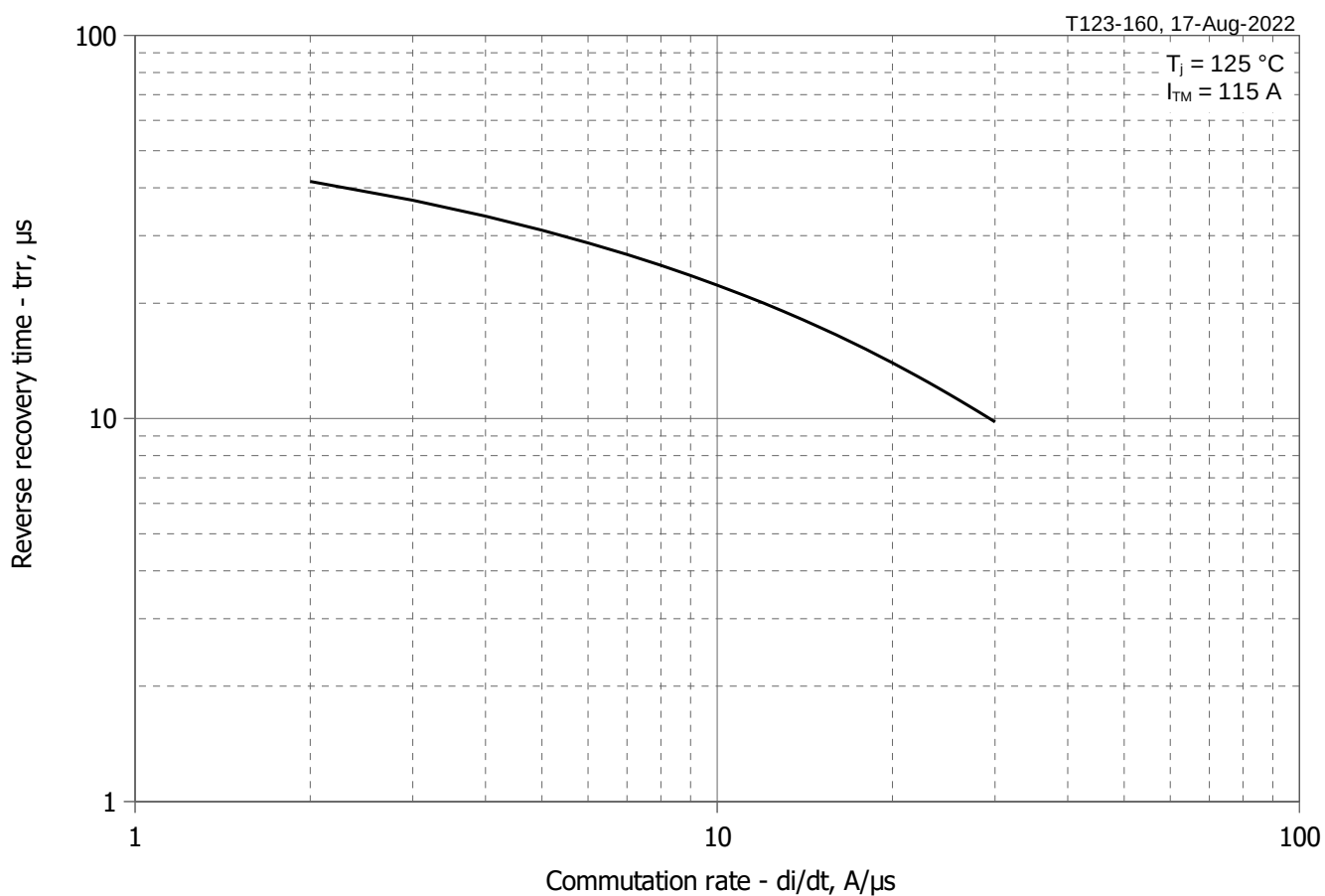


Fig 8 – Maximum recovery time t_{rr} vs. commutation rate di_R/dt (25% chord)

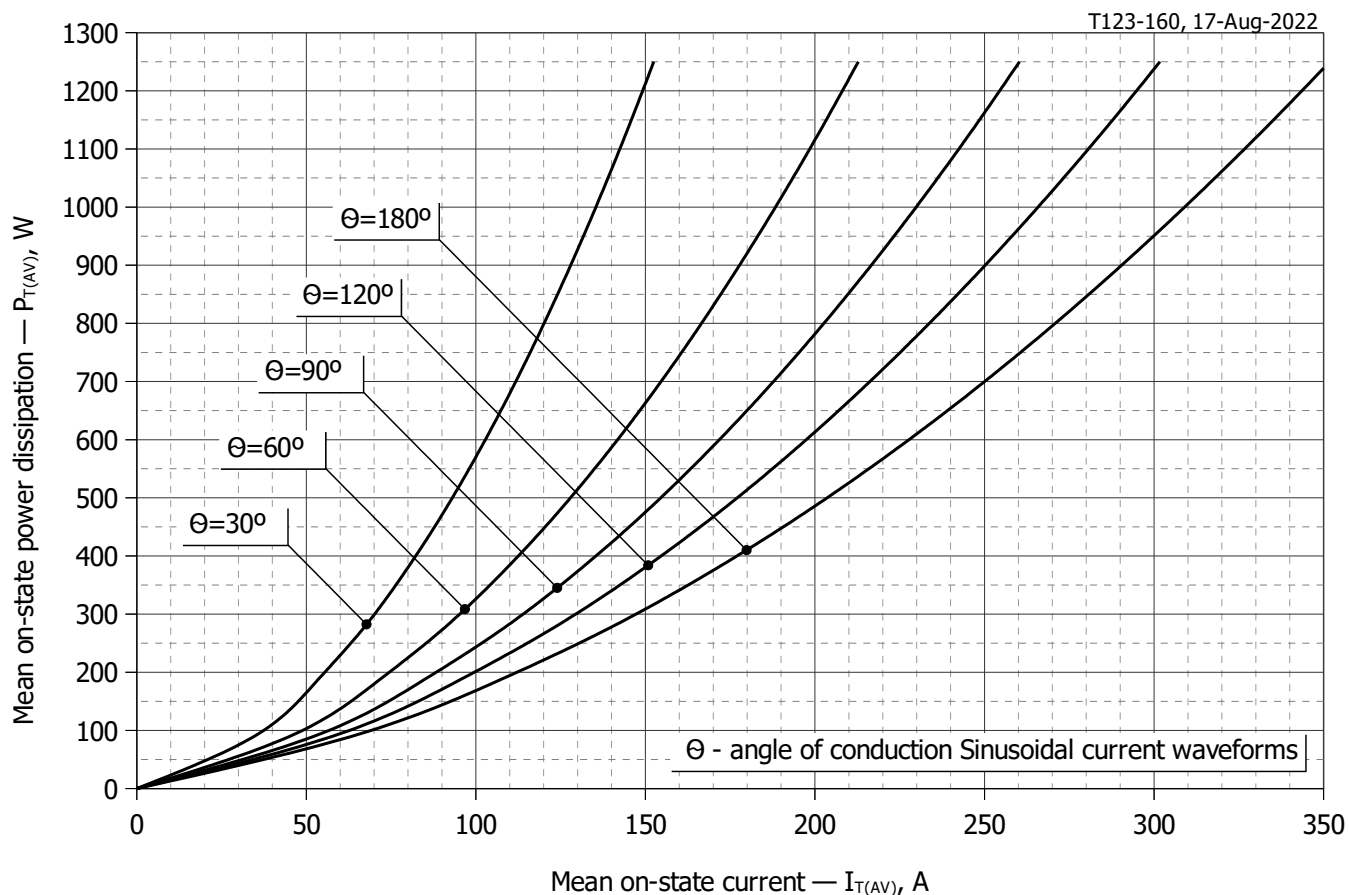


Fig 9 - Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for sinusoidal current waveforms at different conduction angles ($f=50\text{Hz}$)

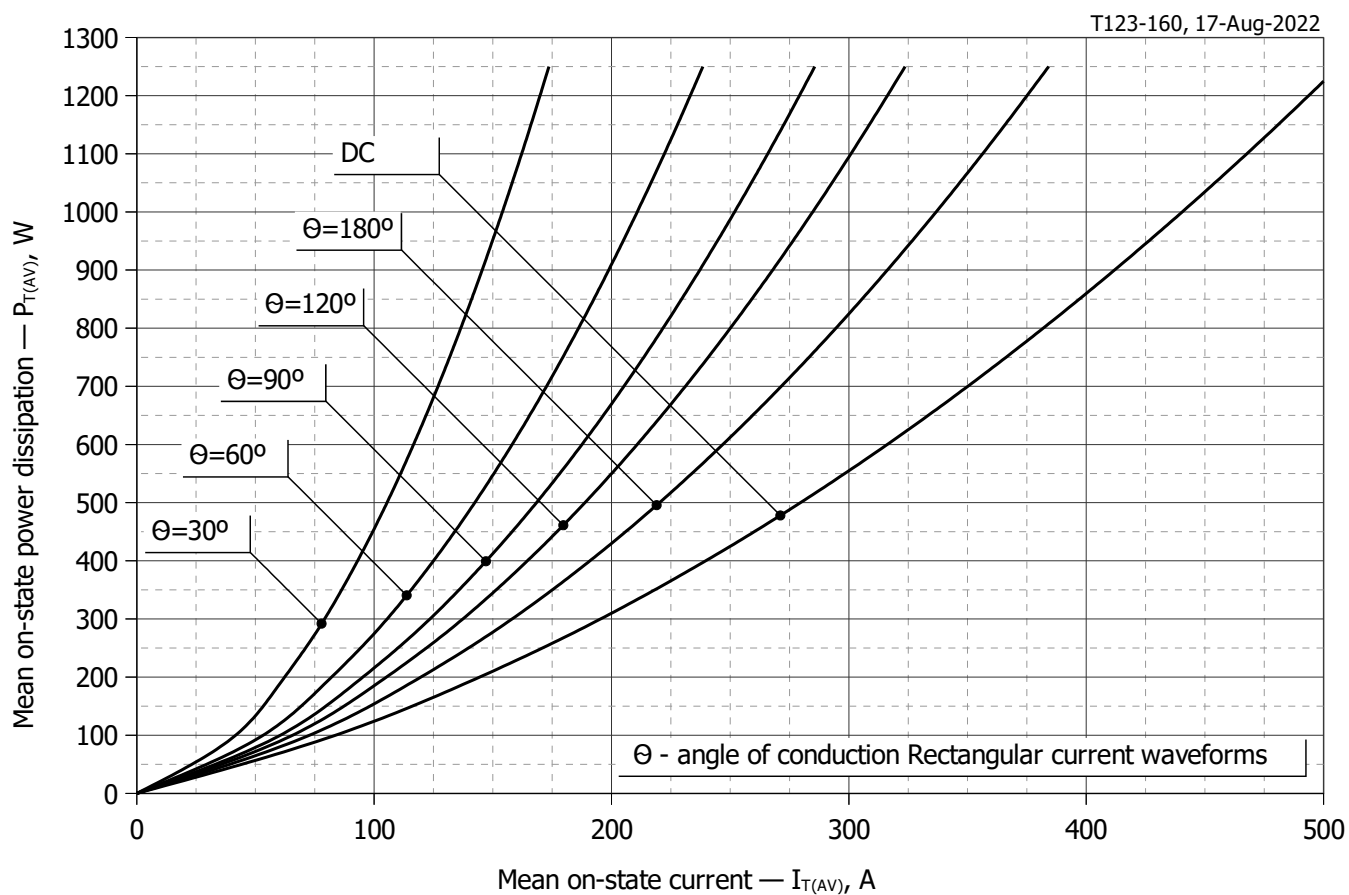


Fig 10 – Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for rectangular current waveforms at different conduction angles and for DC ($f=50\text{Hz}$)

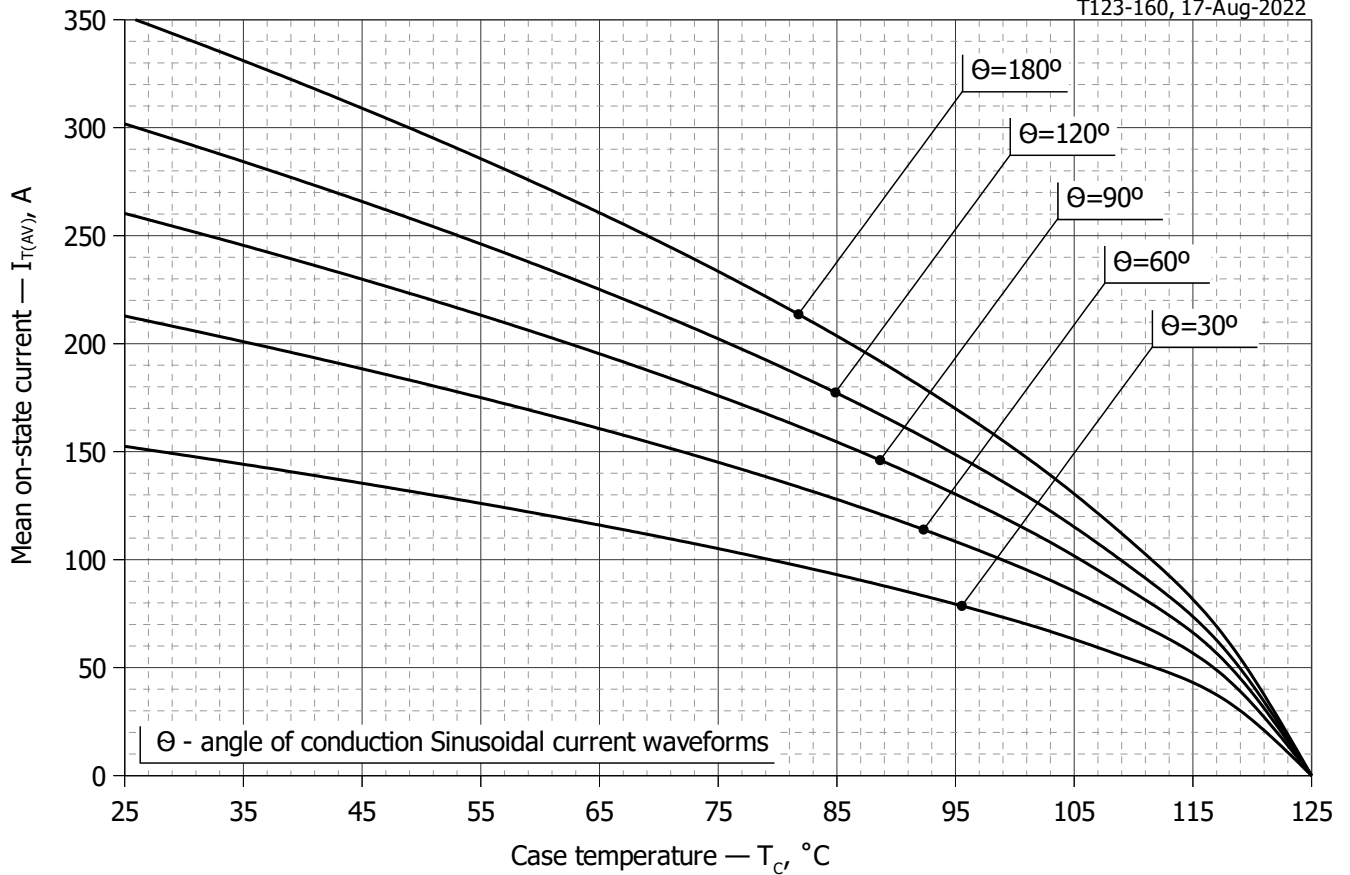


Fig 11 – Mean on-state current I_{TAV} vs. case temperature T_c for sinusoidal current waveforms at different conduction angles ($f=50\text{Hz}$)

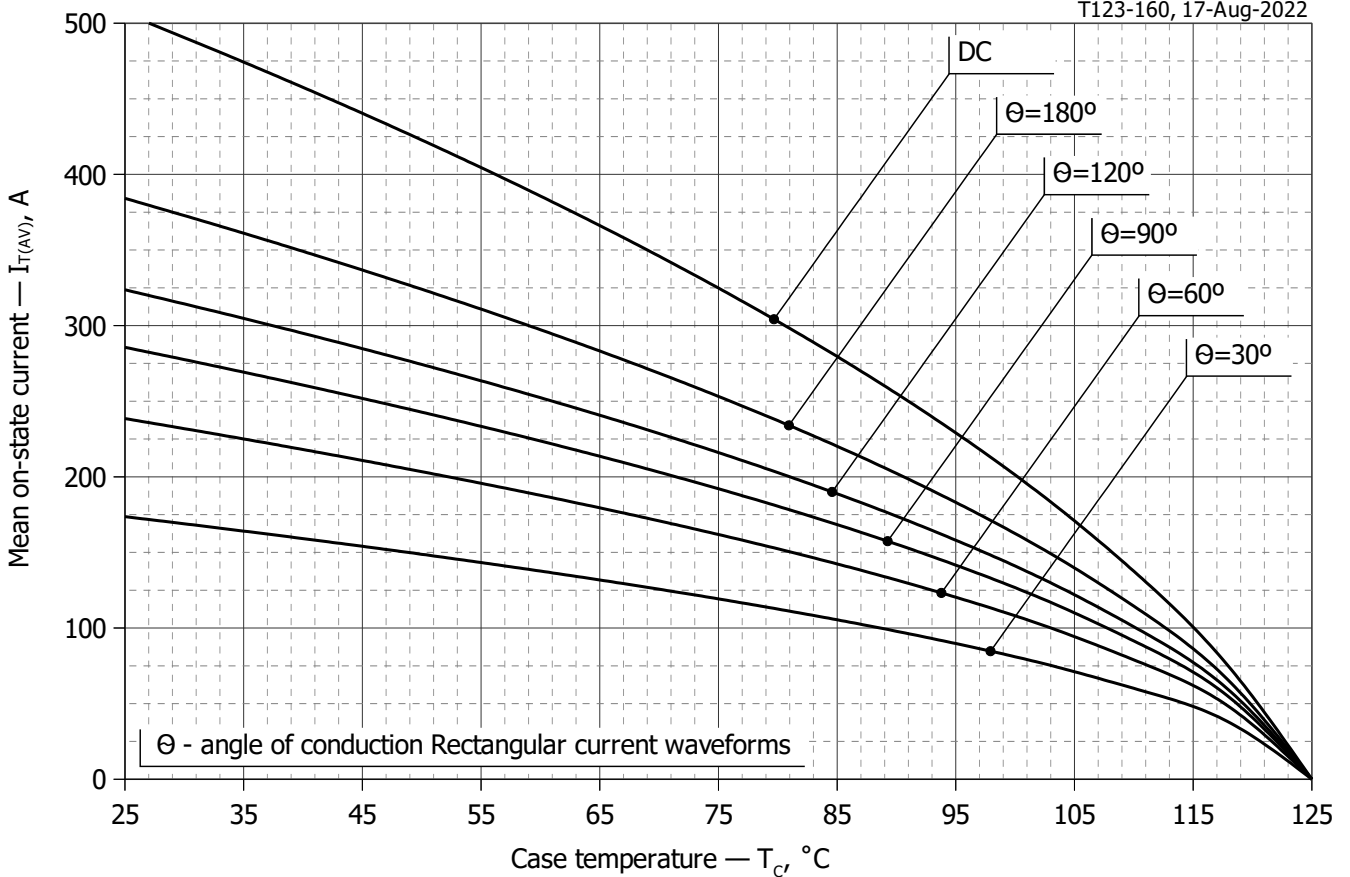


Fig 12 - Mean on-state current I_{TAV} vs. case temperature T_c for rectangular current waveforms at different conduction angles and for DC ($f=50\text{Hz}$)

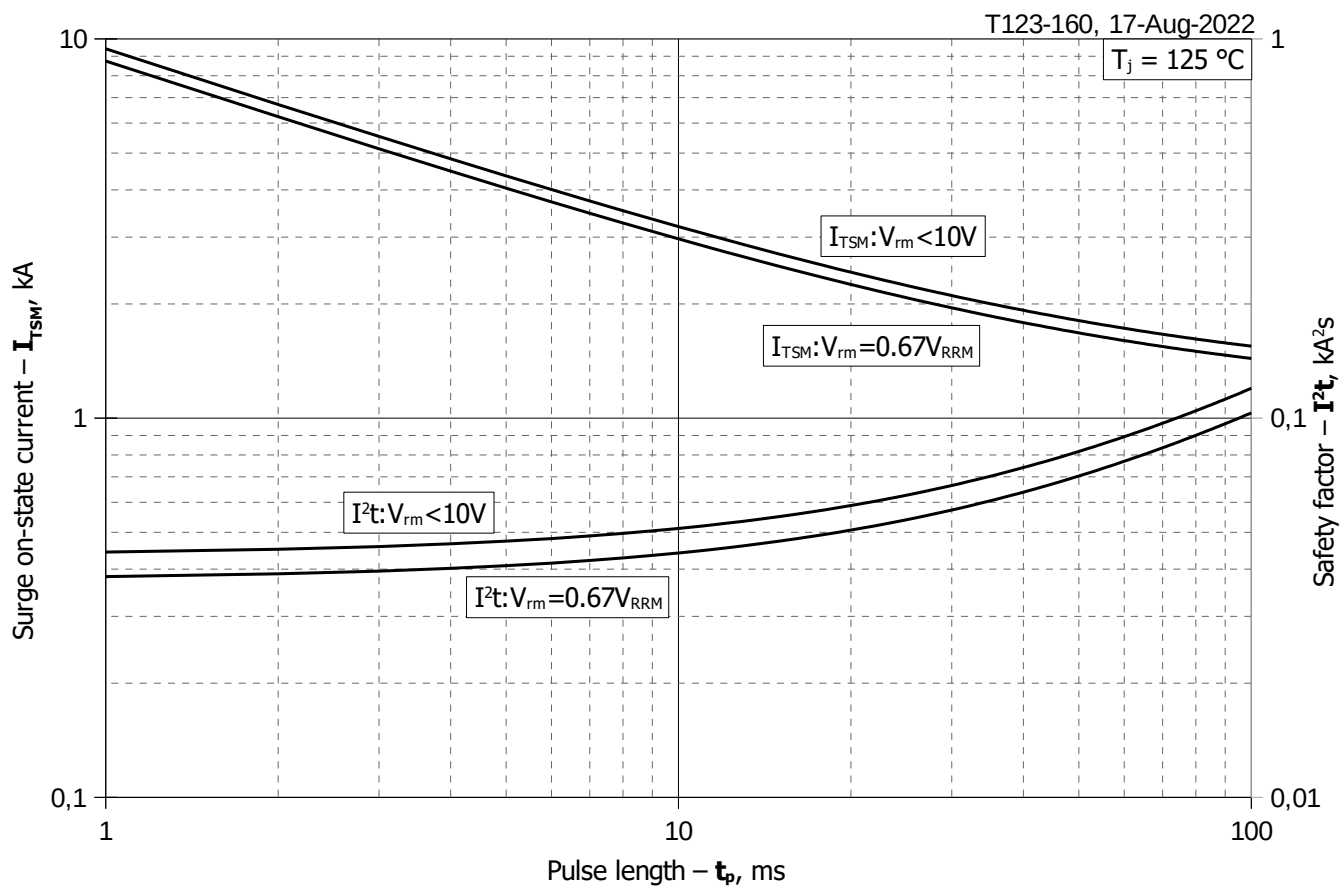


Fig 13 – Maximum surge on-state current I_{TSM} and safety factor I^2t vs. pulse length t_p

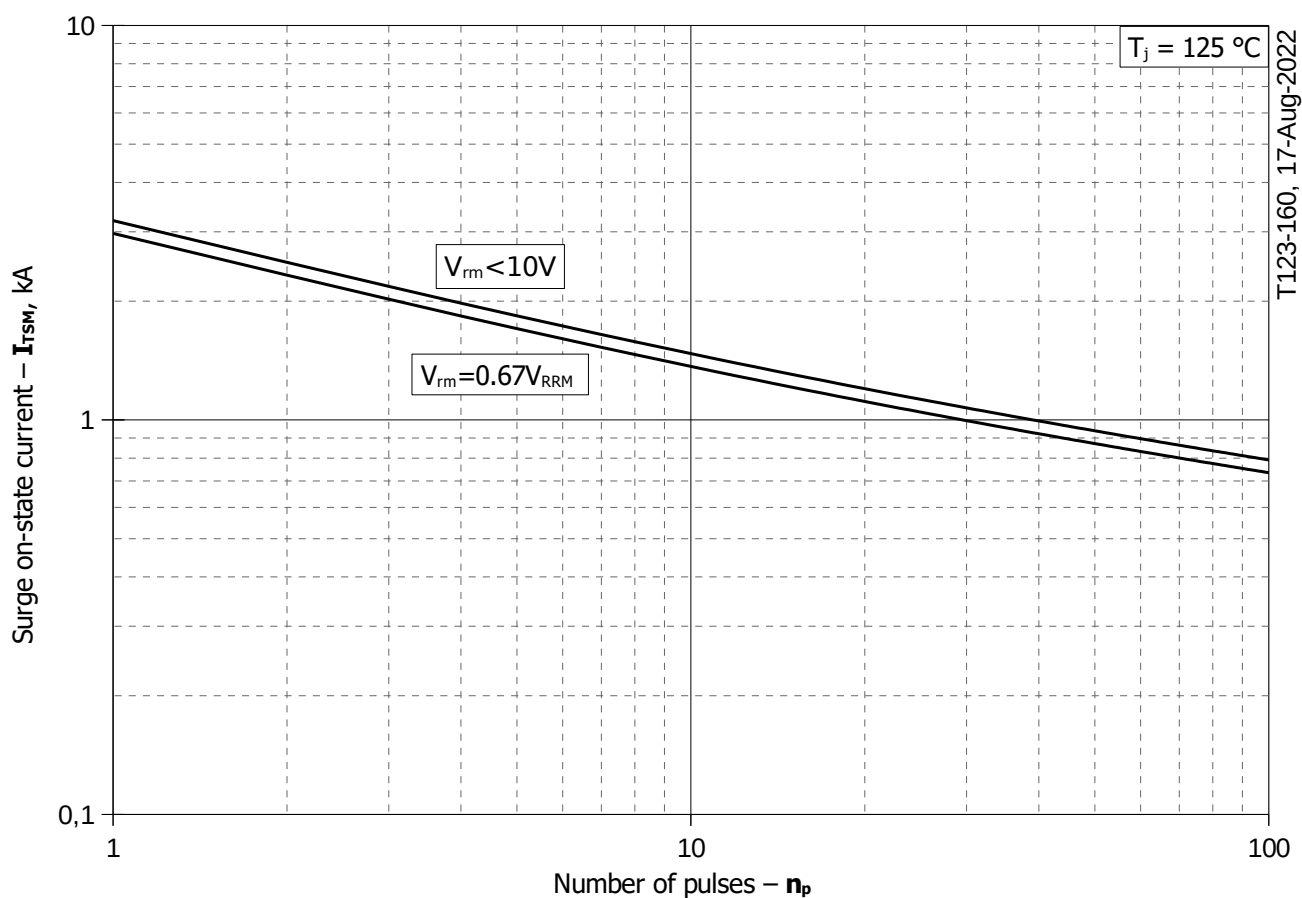


Fig 14 - Maximum surge on-state current I_{TSM} vs. number of pulses n_p